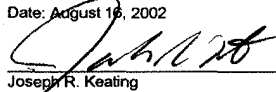


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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Assistant Commissioner for Patents, Washington, D. C. 20231.

Date: August 16, 2002


Joseph R. Keating

2834
#15/C
REVIEWS
8.30.02

PATENT
36856.345

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Masaya WAJIMA et al.

Serial No.: 09/656,106

Filed: September 6, 2000

Title: CHIP ELECTRONIC COMPONENT
AND MOUNTING STRUCTURE OF THE
SAME

Art Unit: 2834

Examiner: J. Gonzalez

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated May 16, 2002, please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please replace claims 1, 9, 13 and 14 with the following claims:

- cl
1. A chip electronic component comprising:
a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;
an electronic component element having electrodes and defining part of said body of the chip electronic component; and

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